

Welcome to E-XFL.COM

#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

### Details

XFI

2 0 0 0 0 0	
Product Status	Discontinued at Digi-Key
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I <sup>2</sup> C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 10x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LFQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101gadfb-30

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 1-1.	List of Ordering Part Numbers
------------	-------------------------------

				(4/12)
Pin count	Package	Data flash	Fields of Application	Ordering Part Number
44 pins	44-pin plastic LQFP	Mounted	А	R5F100FAAFP#V0, R5F100FCAFP#V0, R5F100FDAFP#V0,
	(10 $ imes$ 10 mm, 0.8 mm			R5F100FEAFP#V0, R5F100FFAFP#V0, R5F100FGAFP#V0,
	pitch)			R5F100FHAFP#V0, R5F100FJAFP#V0, R5F100FKAFP#V0,
				R5F100FLAFP#V0
				R5F100FAAFP#X0, R5F100FCAFP#X0, R5F100FDAFP#X0,
				R5F100FEAFP#X0, R5F100FFAFP#X0, R5F100FGAFP#X0,
				R5F100FHAFP#X0, R5F100FJAFP#X0, R5F100FKAFP#X0,
				R5F100FLAFP#X0
			D	R5F100FADFP#V0, R5F100FCDFP#V0, R5F100FDDFP#V0,
				R5F100FEDFP#V0, R5F100FFDFP#V0, R5F100FGDFP#V0,
				R5F100FHDFP#V0, R5F100FJDFP#V0, R5F100FKDFP#V0,
				R5F100FLDFP#V0
				R5F100FADFP#X0, R5F100FCDFP#X0, R5F100FDDFP#X0,
				R5F100FEDFP#X0, R5F100FFDFP#X0, R5F100FGDFP#X0,
				R5F100FHDFP#X0, R5F100FJDFP#X0, R5F100FKDFP#X0,
				R5F100FLDFP#X0
			G	R5F100FAGFP#V0, R5F100FCGFP#V0, R5F100FDGFP#V0,
				R5F100FEGFP#V0, R5F100FFGFP#V0, R5F100FGGFP#V0,
				R5F100FHGFP#V0, R5F100FJGFP#V0
				R5F100FAGFP#X0, R5F100FCGFP#X0, R5F100FDGFP#X0,
				R5F100FEGFP#X0, R5F100FFGFP#X0, R5F100FGGFP#X0,
				R5F100FHGFP#X0, R5F100FJGFP#X0
		Not	А	R5F101FAAFP#V0, R5F101FCAFP#V0, R5F101FDAFP#V0,
		mounted		R5F101FEAFP#V0, R5F101FFAFP#V0, R5F101FGAFP#V0,
				R5F101FHAFP#V0, R5F101FJAFP#V0, R5F101FKAFP#V0,
				R5F101FLAFP#V0
				R5F101FAAFP#X0, R5F101FCAFP#X0, R5F101FDAFP#X0,
				R5F101FEAFP#X0, R5F101FFAFP#X0, R5F101FGAFP#X0,
				R5F101FHAFP#X0, R5F101FJAFP#X0, R5F101FKAFP#X0,
				R5F101FLAFP#X0
			D	R5F101FADFP#V0, R5F101FCDFP#V0, R5F101FDDFP#V0,
				R5F101FEDFP#V0, R5F101FFDFP#V0, R5F101FGDFP#V0,
				R5F101FHDFP#V0, R5F101FJDFP#V0, R5F101FKDFP#V0,
				R5F101FLDFP#V0
				R5F101FADFP#X0, R5F101FCDFP#X0, R5F101FDDFP#X0,
				R5F101FEDFP#X0, R5F101FFDFP#X0, R5F101FGDFP#X0,
				R5F101FHDFP#X0, R5F101FJDFP#X0, R5F101FKDFP#X0,
				R5F101FLDFP#X0

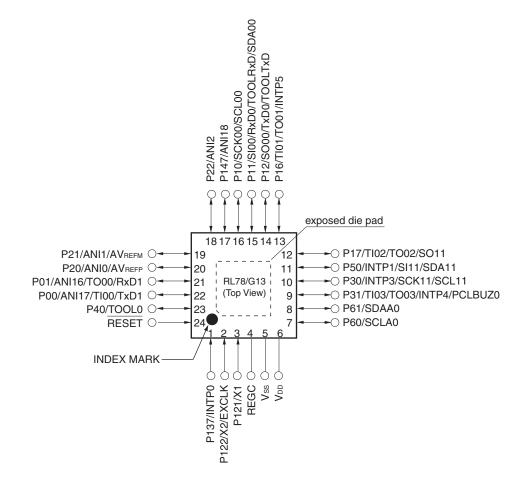
Note For the fields of application, refer to Figure 1-1 Part Number, Memory Size, and Package of RL78/G13.

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.



# 1.3.2 24-pin products

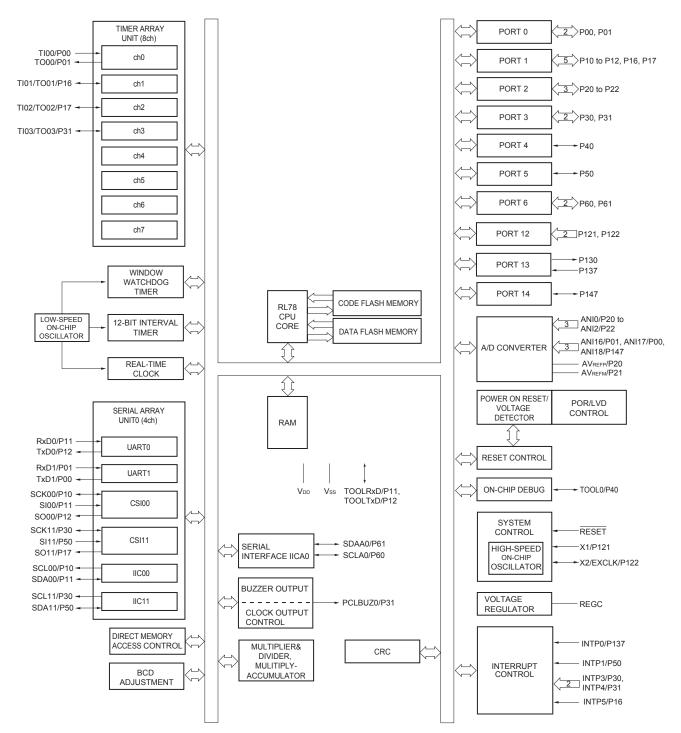
• 24-pin plastic HWQFN (4 × 4 mm, 0.5 mm pitch)



- Caution Connect the REGC pin to Vss via a capacitor (0.47 to 1  $\mu$ F).
- Remarks 1. For pin identification, see 1.4 Pin Identification.
  - 2. It is recommended to connect an exposed die pad to Vss.

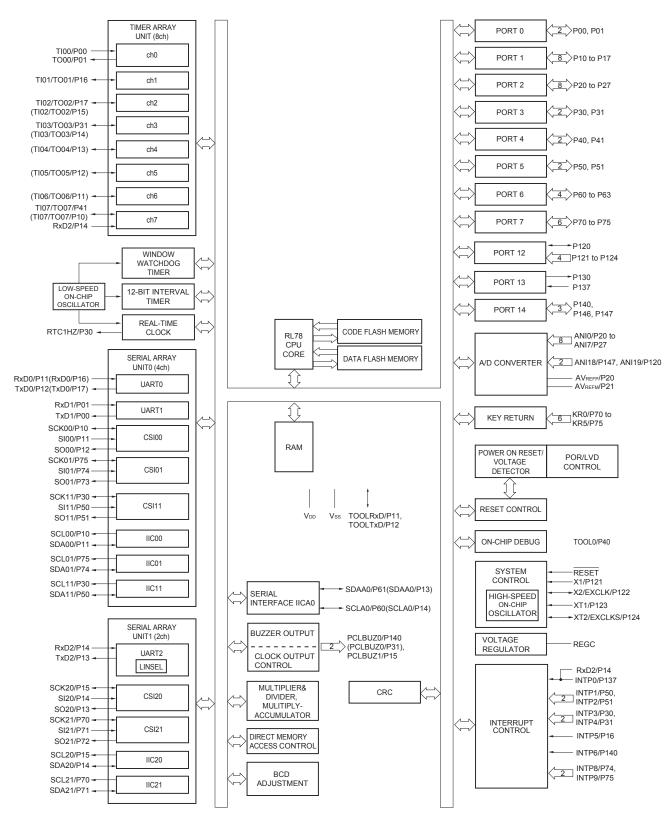


# 1.5.3 25-pin products





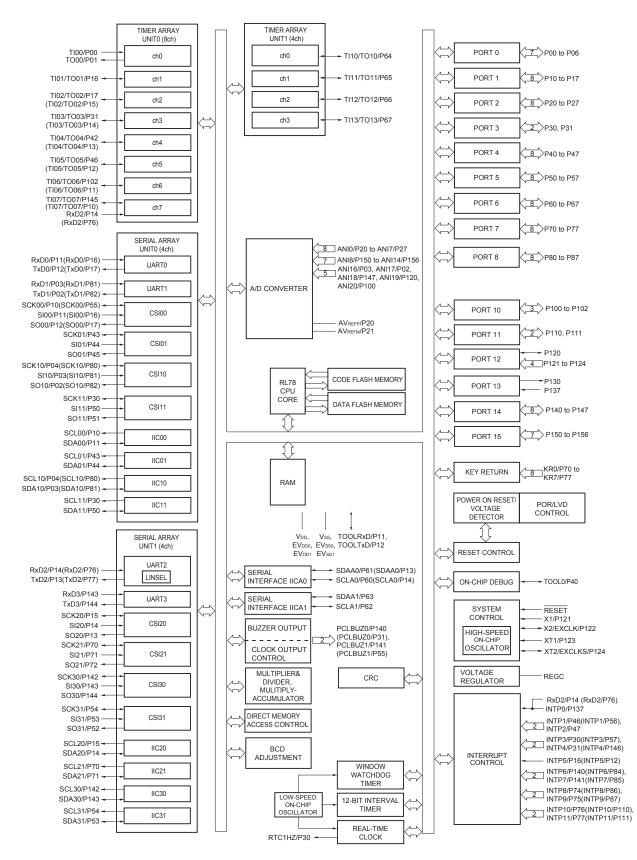
## 1.5.9 48-pin products



**Remark** Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register** (**PIOR**) in the RL78/G13 User's Manual.



# 1.5.13 100-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR) in the RL78/G13 User's Manual.



Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high	VIH1	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		0.8EVDD0		EVDDO	V
	VIH2	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer $4.0 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	2.2		EVDDO	V
		P80, P81, P142, P143	TTL input buffer $3.3 \text{ V} \leq \text{EV}_{\text{DD0}} < 4.0 \text{ V}$	2.0		EVDDO	V
			TTL input buffer $1.6 \text{ V} \leq \text{EV}_{\text{DD0}} < 3.3 \text{ V}$	1.5		EVDDO	V
	VIH3	P20 to P27, P150 to P156	0.7V <sub>DD</sub>		VDD	V	
	VIH4	P60 to P63	0.7EVDD0		6.0	V	
	VIH5	P121 to P124, P137, EXCLK, EXCL	0.8Vdd		VDD	V	
Input voltage, low	VIL1	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		0		0.2EV <sub>DD0</sub>	V
	VIL2	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer 4.0 V $\leq$ EV <sub>DD0</sub> $\leq$ 5.5 V	0		0.8	V
		P80, P81, P142, P143	TTL input buffer 3.3 V $\leq$ EV <sub>DD0</sub> $<$ 4.0 V	0		0.5	V
			TTL input buffer 1.6 V ≤ EV <sub>DD0</sub> < 3.3 V	0		0.32	V
	VIL3	P20 to P27, P150 to P156		0		0.3Vdd	V
	VIL4	P60 to P63		0		0.3EVDD0	V
	VIL5	P121 to P124, P137, EXCLK, EXCL	KS, RESET	0		0.2VDD	V

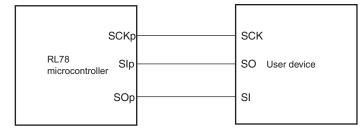
- Caution The maximum value of V<sub>IH</sub> of pins P00, P02 to P04, P10 to P15, P17, P43 to P45, P50, P52 to P55, P71, P74, P80 to P82, P96, and P142 to P144 is EV<sub>DD0</sub>, even in the N-ch open-drain mode.
- **Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



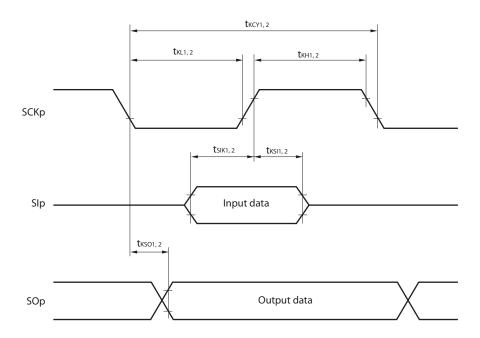
- **Notes 1.** Total current flowing into Vbb, EVbbb, and EVbb1, including the input leakage current flowing when the level of the input pin is fixed to Vbb, EVbb0, and EVbb1, or Vss, EVsso, and EVss1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  - 2. During HALT instruction execution by flash memory.
  - 3. When high-speed on-chip oscillator and subsystem clock are stopped.
  - 4. When high-speed system clock and subsystem clock are stopped.
  - 5. When high-speed on-chip oscillator and high-speed system clock are stopped. When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1). The current flowing into the RTC is included. However, not including the current flowing into the 12-bit interval timer and watchdog timer.
  - 6. Not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
  - 7. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
    - HS (high-speed main) mode: 2.7 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 32 MHz
      - 2.4 V  $\leq$  V\_{DD}  $\leq$  5.5 V@1 MHz to 16 MHz
    - LS (low-speed main) mode: ~~ 1.8 V  $\leq$  V\_{DD}  $\leq$  5.5 V@1 MHz to 8 MHz
    - LV (low-voltage main) mode: 1.6 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 4 MHz
  - 8. Regarding the value for current to operate the subsystem clock in STOP mode, refer to that in HALT mode.
- **Remarks 1.** f<sub>MX</sub>: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  - 2. fin: High-speed on-chip oscillator clock frequency
  - 3. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
  - 4. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is  $T_A = 25^{\circ}C$



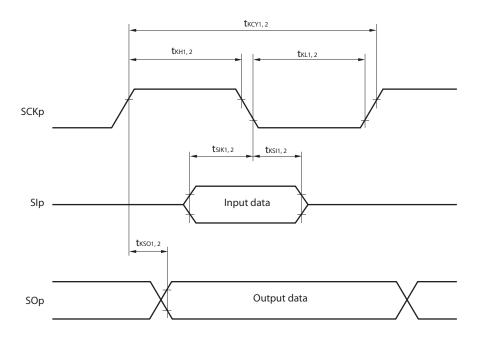
### CSI mode connection diagram (during communication at same potential)

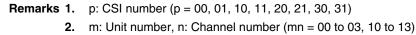


CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)







# (9) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)

Parameter	Symbol	Conditions	HS (high- speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp high-/low-level width	tкн2, tкL2	$\begin{array}{l} 4.0 \ V \leq EV_{DD0} \leq 5.5 \ V, \\ 2.7 \ V \leq V_b \leq 4.0 \ V \end{array}$	tксү2/2 – 12		tксү2/2 - 50		tксү2/2 - 50		ns
		$\begin{array}{l} 2.7 \ V \leq EV_{DD0} < 4.0 \ V, \\ 2.3 \ V \leq V_b \leq 2.7 \ V \end{array}$	tксү2/2 – 18		tксү2/2 - 50		tксү2/2 - 50		ns
		$\label{eq:VDD} \begin{split} 1.8 \ V &\leq E V_{\text{DD0}} < 3.3 \ V, \\ 1.6 \ V &\leq V_b \leq 2.0 \ V^{\text{Note 2}} \end{split}$	tксү2/2 - 50		tксү2/2 - 50		tксү2/2 - 50		ns
SIp setup time (to SCKp↑) <sup>Note 3</sup>	tsik2	$\begin{array}{l} 4.0 \; V \leq E V_{DD0} \leq 5.5 \; V, \\ 2.7 \; V \leq V_b \leq 4.0 \; V \end{array}$	1/fмск + 20		1/fмск + 30		1/fмск + 30		ns
		$\begin{array}{l} 2.7 \ V \leq E V_{DD0} < 4.0 \ V, \\ 2.3 \ V \leq V_b \leq 2.7 \ V \end{array}$	1/fмск + 20		1/fмск + 30		1/fмск + 30		ns
		$\begin{array}{l} 1.8 \ V \leq EV_{DD0} < 3.3 \ V, \\ 1.6 \ V \leq V_b \leq 2.0 \ V^{\text{Note 2}} \end{array}$	1/fмск + 30		1/fмск + 30		1/fмск + 30		ns
Slp hold time (from SCKp↑) <sup>Note 4</sup>	tksi2		1/fмск + 31		1/fмск + 31		1/fмск + 31		ns
Delay time from SCKp↓ to SOp output Note 5	tkso2	$\label{eq:V_def} \begin{array}{l} 4.0 \ V \leq EV_{\text{DD0}} \leq 5.5 \ V, \ 2.7 \ V \leq V_{\text{b}} \leq 4.0 \\ V, \\ C_{\text{b}} = 30 \ pF, \ R_{\text{b}} = 1.4 \ k\Omega \end{array}$		2/fмск + 120		2/fмск + 573		2/fмск + 573	ns
		$\label{eq:V_def} \begin{array}{l} 2.7 \; V \leq EV_{\text{DD0}} < 4.0 \; V, \; 2.3 \; V \leq V_{b} \leq 2.7 \\ V, \\ C_{b} = 30 \; pF, \; R_{b} = 2.7 \; k\Omega \end{array}$		2/fмск + 214		2/fмск + 573		2/fмск + 573	ns
		$ \begin{split} & 1.8 \ V \leq EV_{DD0} < 3.3 \ V, \\ & 1.6 \ V \leq V_b \leq 2.0 \ V^{\text{Note 2}}, \\ & C_b = 30 \ pF, \ R_b = 5.5 \ k\Omega \end{split} $		2/fмск + 573		2/fмск + 573		2/fмск + 573	ns

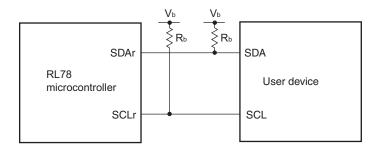
Notes 1. Transfer rate in the SNOOZE mode : MAX. 1 Mbps

- **2.** Use it with  $EV_{DD0} \ge V_b$ .
- 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- 4. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- 5. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp<sup>↑</sup>" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- Caution Select the TTL input buffer for the SIp pin and the N-ch open drain output (V<sub>DD</sub> tolerance (for the 20- to 52-pin products)/EV<sub>DD</sub> tolerance (for the 64- to 128-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V<sub>IH</sub> and V<sub>IL</sub>, see the DC characteristics with TTL input buffer selected.

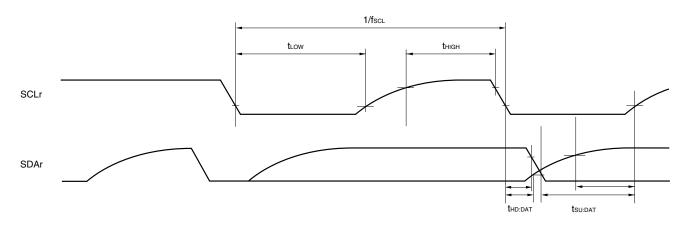
(Remarks are listed on the next page.)



### Simplified I<sup>2</sup>C mode connection diagram (during communication at different potential)



### Simplified I<sup>2</sup>C mode serial transfer timing (during communication at different potential)



- **Remarks 1.** R<sub>b</sub>[Ω]:Communication line (SDAr, SCLr) pull-up resistance, C<sub>b</sub>[F]: Communication line (SDAr, SCLr) load capacitance, V<sub>b</sub>[V]: Communication line voltage
  - 2. r: IIC number (r = 00, 01, 10, 20, 30, 31), g: PIM, POM number (g = 0, 1, 4, 5, 8, 14)
  - 3. fMCK: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number,

n: Channel number (mn = 00, 01, 02, 10, 12, 13)



# 3. ELECTRICAL SPECIFICATIONS (G: INDUSTRIAL APPLICATIONS $T_A = -40$ to +105°C)

This chapter describes the following electrical specifications.

Target products G: Industrial applications  $T_A = -40$  to  $+105^{\circ}C$ R5F100xxGxx

- Cautions 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.
  - 2. With products not provided with an EVDD0, EVDD1, EVSS0, or EVSS1 pin, replace EVDD0 and EVDD1 with VDD, or replace EVSS0 and EVSS1 with VSS.
  - 3. The pins mounted depend on the product. Refer to 2.1 Port Function to 2.2.1 Functions for each product.
  - Please contact Renesas Electronics sales office for derating of operation under T<sub>A</sub> = +85°C to +105°C. Derating is the systematic reduction of load for the sake of improved reliability.

**Remark** When RL78/G13 is used in the range of  $T_A = -40$  to +85°C, see **CHAPTER 2 ELECTRICAL SPECIFICATIONS (T<sub>A</sub> = -40 to +85°C)**.

There are following differences between the products "G: Industrial applications ( $T_A = -40$  to  $+105^{\circ}C$ )" and the products "A: Consumer applications, and D: Industrial applications".

Parameter	Ap	pplication
	A: Consumer applications, D: Industrial applications	G: Industrial applications
Operating ambient temperature	T <sub>A</sub> = -40 to +85°C	T <sub>A</sub> = -40 to +105°C
Operating mode Operating voltage range	$\begin{array}{l} \text{HS (high-speed main) mode:} \\ \text{2.7 V} \leq V_{\text{DD}} \leq 5.5 \ \text{V@1 MHz to 32 MHz} \\ \text{2.4 V} \leq V_{\text{DD}} \leq 5.5 \ \text{V@1 MHz to 16 MHz} \\ \text{LS (low-speed main) mode:} \\ \text{1.8 V} \leq V_{\text{DD}} \leq 5.5 \ \text{V@1 MHz to 8 MHz} \\ \text{LV (low-voltage main) mode:} \\ \text{1.6 V} \leq V_{\text{DD}} \leq 5.5 \ \text{V@1 MHz to 4 MHz} \end{array}$	HS (high-speed main) mode only: 2.7 V $\leq$ V <sub>DD</sub> $\leq$ 5.5 V@1 MHz to 32 MHz 2.4 V $\leq$ V <sub>DD</sub> $\leq$ 5.5 V@1 MHz to 16 MHz
High-speed on-chip oscillator clock accuracy	$\begin{array}{l} 1.8 \ V \leq V_{DD} \leq 5.5 \ V \\ \pm 1.0\% @ \ T_{A} = -20 \ to \ +85^{\circ}C \\ \pm 1.5\% @ \ T_{A} = -40 \ to \ -20^{\circ}C \\ 1.6 \ V \leq V_{DD} < 1.8 \ V \\ \pm 5.0\% @ \ T_{A} = -20 \ to \ +85^{\circ}C \\ \pm 5.5\% @ \ T_{A} = -40 \ to \ -20^{\circ}C \end{array}$	$\begin{array}{l} 2.4 \ V \leq V_{DD} \leq 5.5 \ V \\ \pm 2.0\% @ \ T_{A} = +85 \ to \ +105^{\circ}C \\ \pm 1.0\% @ \ T_{A} = -20 \ to \ +85^{\circ}C \\ \pm 1.5\% @ \ T_{A} = -40 \ to \ -20^{\circ}C \end{array}$
Serial array unit	UART CSI: fcLk/2 (supporting 16 Mbps), fcLk/4 Simplified I <sup>2</sup> C communication	UART CSI: fcLk/4 Simplified I <sup>2</sup> C communication
IICA	Normal mode Fast mode Fast mode plus	Normal mode Fast mode
Voltage detector	Rise detection voltage: 1.67 V to 4.06 V (14 levels) Fall detection voltage: 1.63 V to 3.98 V (14 levels)	Rise detection voltage: 2.61 V to 4.06 V (8 levels) Fall detection voltage: 2.55 V to 3.98 V (8 levels)

(Remark is listed on the next page.)



Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, Iow <sup>№061</sup>	Iol1	Per pin for P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147				8.5 <sup>Note 2</sup>	mA
		Per pin for P60 to P63				15.0 <sup>Note 2</sup>	mA
		P37,	$4.0~V \leq EV_{\text{DD0}} \leq 5.5~V$			40.0	mA
			$2.7~V \leq EV_{\text{DD0}} < 4.0~V$			15.0	mA
	P125 to P127 (When duty ≤	P40 to P47, P102 to P106, P120, P125 to P127, P130, P140 to P145 (When duty $\leq 70\%$ Note 3)	$2.4~V \leq EV_{\text{DD0}} < 2.7~V$			9.0	mA
		P31, P50 to P57, P60 to P67,	$4.0~V \leq EV_{\text{DD0}} \leq 5.5~V$			40.0	mA
			$2.7~V \leq EV_{\text{DD0}} < 4.0~V$			35.0	mA
		P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to P117, P146, P147 (When duty $\leq 70\%$ <sup>Note 3</sup> )	$2,4~V \leq EV_{DD0} < 2.7~V$			20.0	mA
	Total of all pins (When duty $\leq$ 70% <sup>Note 3</sup> )				80.0	mA	
	IOL2	Per pin for P20 to P27, P150 to P156			_	0.4 Note 2	mA
		Total of all pins (When duty ≤ 70% <sup>Note 3</sup> )	$2,4~V \le V_{\text{DD}} \le 5.5~V$			5.0	mA

### $(T_A = -40 \text{ to } +105^{\circ}\text{C}, 2.4 \text{ V} \le \text{EV}_{\text{DD0}} = \text{EV}_{\text{DD1}} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}, \text{ Vss} = \text{EV}_{\text{SS0}} = \text{EV}_{\text{SS1}} = 0 \text{ V})$ (2/5)

- **Notes 1**. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the EVsso, EVss1 and Vss pin.
  - 2. Do not exceed the total current value.
  - **3.** Specification under conditions where the duty factor  $\leq$  70%.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins =  $(I_{OL} \times 0.7)/(n \times 0.01)$ 

<Example> Where n = 80% and  $I_{OL} = 10.0 \text{ mA}$ 

Total output current of pins =  $(10.0 \times 0.7)/(80 \times 0.01) \approx 8.7$  mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



- **Notes 1.** Total current flowing into VDD, EVDDD, and EVDD1, including the input leakage current flowing when the level of the input pin is fixed to VDD, EVDDD, and EVDD1, or Vss, EVsso, and EVss1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  - 2. When high-speed on-chip oscillator and subsystem clock are stopped.
  - 3. When high-speed system clock and subsystem clock are stopped.
  - **4.** When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the 12-bit interval timer and watchdog timer.
  - **5.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 32 MHz

2.4 V  $\leq$  V<sub>DD</sub>  $\leq$  5.5 V@1 MHz to 16 MHz

- **Remarks 1.** fMX: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  - 2. fin: High-speed on-chip oscillator clock frequency
  - 3. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
  - 4. Except subsystem clock operation, temperature condition of the TYP. value is  $T_A = 25^{\circ}C$



Parameter	Symbol	Conditions		HS (high-speed main) Mode	
			MIN.	MAX.	
SCLr clock frequency	fscL	$2.7~V \leq EV_{\text{DD0}} \leq 5.5~V,$		400 Note1	kHz
		$C_b = 50 \text{ pF}, \text{ R}_b = 2.7 \text{ k}\Omega$			
		$2.4~V \leq EV_{\text{DD0}} \leq 5.5~V,$		100 Note1	kHz
		$C_b = 100 \text{ pF}, \text{ R}_b = 3  \text{k}\Omega$			
Hold time when SCLr = "L"	t∟ow	$2.7~V \leq EV_{\text{DD0}} \leq 5.5~V,$	1200		ns
		$C_b = 50 \text{ pF}, \text{ R}_b = 2.7 \text{ k}\Omega$			
		$2.4~V \leq EV_{\text{DD0}} \leq 5.5~V,$	4600		ns
		$C_b = 100 \text{ pF}, R_b = 3  k\Omega$			
Hold time when SCLr = "H"	tніgн	$2.7~V \leq EV_{\text{DD0}} \leq 5.5~V,$	1200		ns
		$C_b = 50 \text{ pF}, \text{R}_b = 2.7 \text{ k}\Omega$			
		$2.4~V \leq EV_{\text{DD0}} \leq 5.5~V,$	4600		ns
		$C_b = 100 \text{ pF}, \text{ R}_b = 3 \text{ k}\Omega$			
Data setup time (reception)	tsu:dat	$2.7~V \leq EV_{\text{DD0}} \leq 5.5~V,$	1/fмск + 220		ns
		$C_b = 50 \text{ pF}, \text{ R}_b = 2.7 \text{ k}\Omega$	Note2		
		$2.4~V \leq EV_{\text{DD}} \leq 5.5~V,$	1/fмск + 580		ns
		$C_b = 100 \text{ pF}, R_b = 3 \text{ k}\Omega$	Note2		
Data hold time (transmission)	thd:dat	$2.7~V \leq EV_{\text{DD0}} \leq 5.5~V,$	0	770	ns
		$C_b$ = 50 pF, $R_b$ = 2.7 k $\Omega$			
		$2.4~V \leq EV_{\text{DD0}} \leq 5.5~V,$	0	1420	ns
		$C_b = 100 \text{ pF}, \text{ R}_b = 3  \text{k}\Omega$			

### (4) During communication at same potential (simplified l<sup>2</sup>C mode) (T<sub>A</sub> = -40 to +105°C, 2.4 V $\leq$ EV<sub>DD0</sub> = EV<sub>DD1</sub> $\leq$ V<sub>DD</sub> $\leq$ 5.5 V, Vss = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

- Notes 1. The value must also be equal to or less than  $f_{MCK}/4$ .
  - **2.** Set the fMCK value to keep the hold time of SCLr = "L" and SCLr = "H".
- Caution Select the normal input buffer and the N-ch open drain output (V<sub>DD</sub> tolerance (for the 20- to 52-pin products)/EV<sub>DD</sub> tolerance (for the 64- to 100-pin products)) mode for the SDAr pin and the normal output mode for the SCLr pin by using port input mode register g (PIMg) and port output mode register h (POMh).

(Remarks are listed on the next page.)



### (5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (1/2) ( $T_A = -40$ to $+105^{\circ}C$ , 2.4 V $\leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5$ V. Vss = $EV_{SS0} = EV_{SS1} = 0$ V)

Parameter	Symbol		Conditions		HS (high-speed main) Mode		Unit
					MIN.	MAX.	
Transfer rate		Reception	$4.0 \ V \ \leq \ EV_{\text{DD0}} \ \leq \ 5.5$			fмск/12 <sup>Note 1</sup>	bps
			V, $2.7 \text{ V} \leq V_b \leq 4.0 \text{ V}$	Theoretical value of the maximum transfer rate fcLK = 32 MHz, fMCK = fcLK		2.6	Mbps
			$2.7 V \leq EV_{DD0} < 4.0$			fмск/12 <sup>Note 1</sup>	bps
			V, $2.3 \text{ V} \leq V_b \leq 2.7 \text{ V}$	Theoretical value of the maximum transfer rate fcLK = 32 MHz, fMCK = fcLK		2.6	Mbps
			$\begin{array}{l} 2.4 \hspace{.1cm} V \hspace{.1cm} \leq \hspace{.1cm} EV_{DD0} \hspace{.1cm} < \hspace{.1cm} 3.3 \\ V, \end{array}$			fмск/12 Notes 1,2	bps
			$1.6~V \leq V_b \leq 2.0~V$	Theoretical value of the maximum transfer rate fcLk = 32 MHz, fMck = fcLk		2.6	Mbps

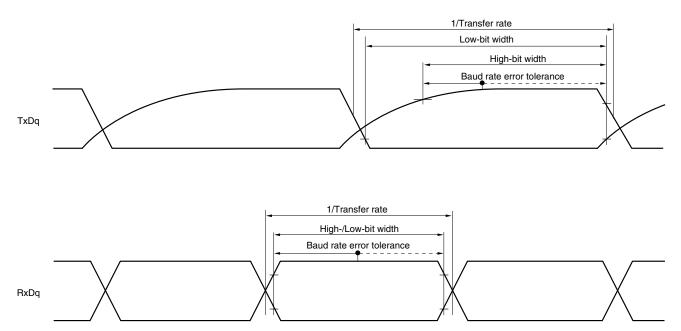
Notes 1. Transfer rate in the SNOOZE mode is 4800 bps only.

- 2. The following conditions are required for low voltage interface when  $E_{VDD0}$  <  $V_{DD}.$  2.4 V  $\leq$   $EV_{DD0}$  < 2.7 V : MAX. 1.3 Mbps
- Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (VDD tolerance (for the 20- to 52-pin products)/EVDD tolerance (for the 64- to 100-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For VIH and VIL, see the DC characteristics with TTL input buffer selected.
- **Remarks 1.**  $V_{b}[V]$ : Communication line voltage
  - **2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)
  - 3. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13)

4. UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.





UART mode bit width (during communication at different potential) (reference)

 Remarks 1.
 Rb[Ω]:Communication line (TxDq) pull-up resistance,

 Cb[F]: Communication line (TxDq) load capacitance, Vb[V]: Communication line voltage

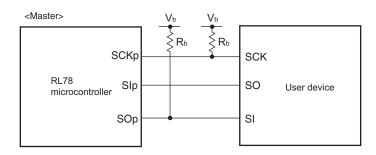
- **2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)
- 3. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

**4.** UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.



### CSI mode connection diagram (during communication at different potential)



- **Remarks 1.** R<sub>b</sub>[Ω]:Communication line (SCKp, SOp) pull-up resistance, C<sub>b</sub>[F]: Communication line (SCKp, SOp) load capacitance, V<sub>b</sub>[V]: Communication line voltage
  - 2. p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number , n: Channel number (mn = 00, 01, 02, 10, 12, 13), g: PIM and POM number (g = 0, 1, 4, 5, 8, 14)
  - 3. fMCK: Serial array unit operation clock frequency (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).
    m: Unit number, n: Channel number (mn = 00))
  - **4.** CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.



3.6.5 Power supply voltage rising slope characteristics

### $(T_A = -40 \text{ to } +105^{\circ}\text{C}, \text{Vss} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	SVDD				54	V/ms

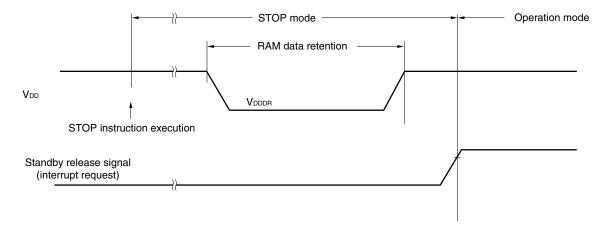
Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until  $V_{DD}$  reaches the operating voltage range shown in 3.4 AC Characteristics.

### 3.7 RAM Data Retention Characteristics

### $(T_A = -40 \text{ to } +105^{\circ}\text{C}, \text{Vss} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	VDDDR		1.44 <sup>Note</sup>		5.5	V

**Note** This depends on the POR detection voltage. For a falling voltage, data in RAM are retained until the voltage reaches the level that triggers a POR reset but not once it reaches the level at which a POR reset is generated.

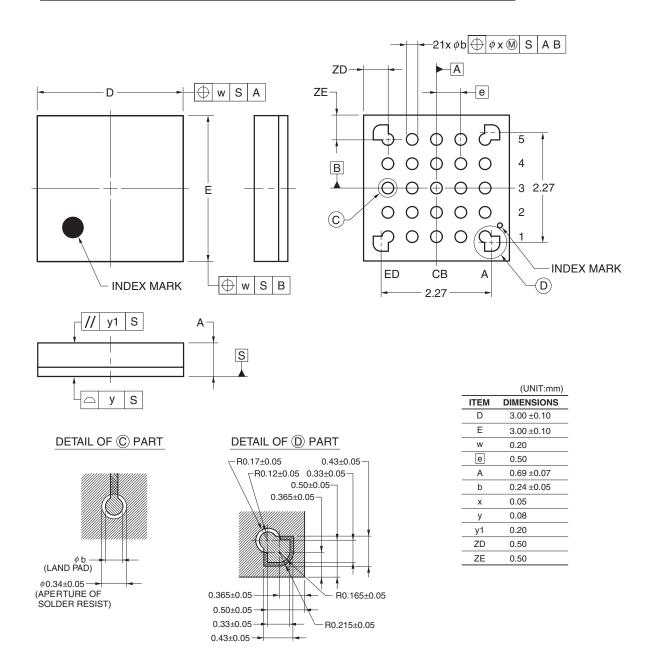




# 4.3 25-pin Products

R5F1008AALA, R5F1008CALA, R5F1008DALA, R5F1008EALA R5F1018AALA, R5F1018CALA, R5F1018DALA, R5F1018EALA R5F1008AGLA, R5F1008CGLA, R5F1008DGLA, R5F1008EGLA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-WFLGA25-3x3-0.50	PWLG0025KA-A	P25FC-50-2N2-2	0.01



©2012 Renesas Electronics Corporation. All rights reserved.

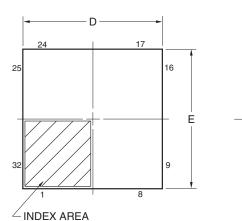


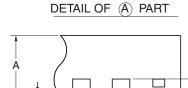
C<sub>2</sub>

# 4.5 32-pin Products

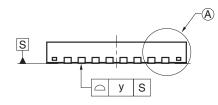
R5F100BAANA, R5F100BCANA, R5F100BDANA, R5F100BEANA, R5F100BFANA, R5F100BGANA R5F101BAANA, R5F101BCANA, R5F101BDANA, R5F101BEANA, R5F101BFANA, R5F101BGANA R5F100BADNA, R5F100BCDNA, R5F100BDDNA, R5F100BEDNA, R5F100BFDNA, R5F100BGDNA R5F101BADNA, R5F101BCDNA, R5F101BDDNA, R5F101BEDNA, R5F101BFDNA, R5F101BGDNA R5F100BAGNA, R5F100BCGNA, R5F100BDGNA, R5F100BEGNA, R5F100BFGNA, R5F100BGGNA

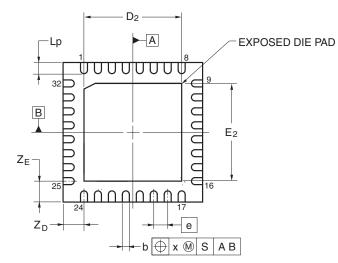
JEITA Package code	RENESAS code	Previous code	MASS (TYP.)[g]
P-HWQFN32-5x5-0.50	PWQN0032KB-A	P32K8-50-3B4-5	0.06





A<sub>1</sub>





Referance	Dimension in Millimeters			
Symbol	Min	Nom	Max	
D	4.95	5.00	5.05	
E	4.95	5.00	5.05	
А			0.80	
A <sub>1</sub>	0.00			
b	0.18	0.25	0.30	
е		0.50		
Lp	0.30	0.40	0.50	
х			0.05	
у			0.05	
ZD		0.75		
Z <sub>E</sub>		0.75	—	
C2	0.15	0.20	0.25	
D <sub>2</sub>		3.50		
E <sub>2</sub>		3.50		

©2013 Renesas Electronics Corporation. All rights reserved.

R01DS0131EJ0330 Rev.3.30 Mar 31, 2016

